

Upgrade of the ALICE-TPC read-out electronics

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for the ALICE collaboration

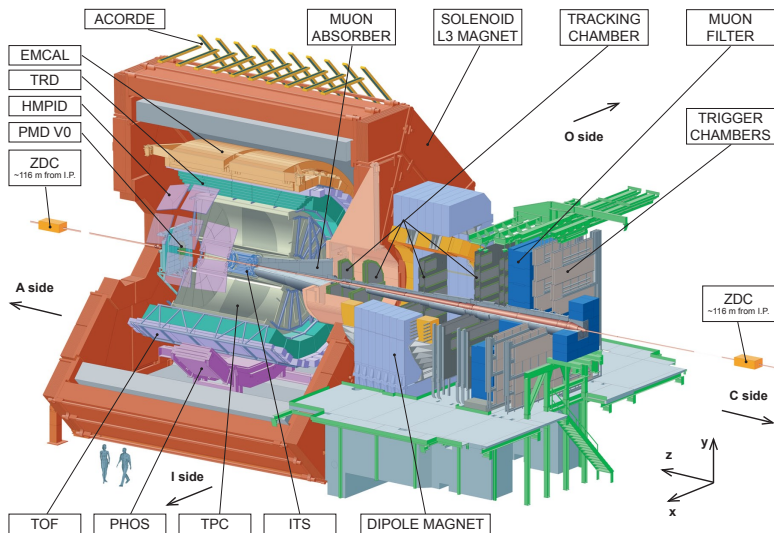
CERN

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September 21st, 2010

Outline

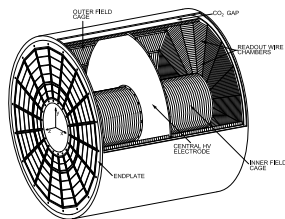
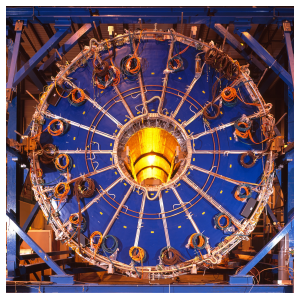
- ▶ Overview of ALICE and its TPC
- ▶ Current read-out and performance
- ▶ Proposed upgrade & first prototype
- ▶ Planning

ALICE



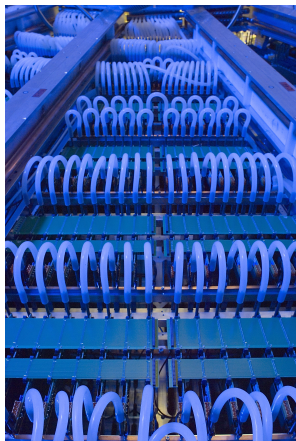
The TPC – key facts

- ▶ pseudo-rapidity coverage: $|\eta| < 0.9$ or $|\eta| < 1.5$ for full and 1/3 of radial track length, respectively
- ▶ active volume: $-2497 < z < 2497$ mm times $848 < r < 2466$ mm
- ▶ read-out chambers: $2 \times 2 \times 18$ (side, radial and azimuthal segmentation) multi-wire proportional chambers
- ▶ gas: Ne-CO₂-N₂ [85.7–9.5–4.8]
- ▶ drift-time: 96 μ s (nominal)



Electronics

- ▶ number of pads: 557,568; distributed over:
 - ▶ 4,536 front-end cards (FECs)
 - ▶ 216 independent read-out partitions:
 - ▶ 2 sides times
 - ▶ 18 sectors (azimuthal) times
 - ▶ 6 partitions (radial) times
 - ▶ 18, 25, 18, 20, 20, 20 FECs (inner to outer)
- ▶ full parallel/concurrent operation
- ▶ sampling:
 - ▶ 10 bit at 10 MSPS
 - ▶ up to 1,008 samples
- ▶ multiple event buffering: 4 events
- ▶ (very) raw event size: 700 MByte



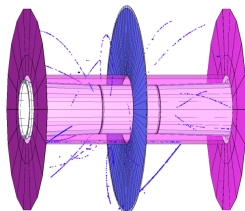
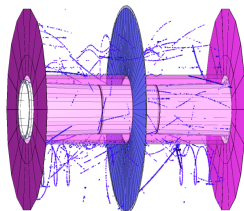
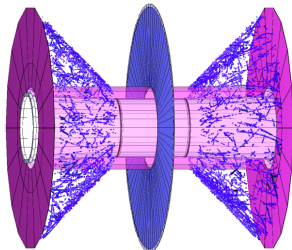
The front-end card (FEC)

- ▶ 128 channels
- ▶ components:
 - ▶ 8 PASAs (pre-amplifier and shaper)
 - ▶ 8 ALTROs (ADC, DSP and event buffering)
 - ▶ board controller (BC)
- ▶ interface:
 - ▶ 40 + 5 bit (data + control) wide bus (GTL)
 - ▶ triggers
 - ▶ L1 (GTL)
 - ▶ L2 (GTL)
 - ▶ clocks
 - ▶ read-out (GTL)
 - ▶ sampling (PECL)
 - ▶ 4-wire serial I²C-like slow control bus (GTL)
 - ▶ card-switch line (CMOS)



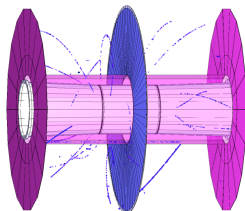
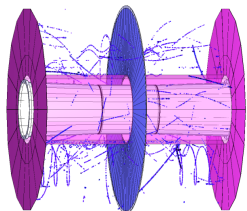
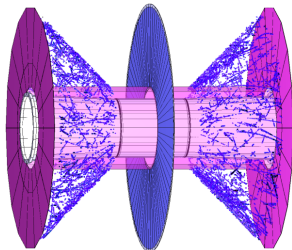
Foreseen operating scenarios

- ▶ proton-proton
 - ▶ isolated events
 - ▶ low interaction rate
 - ▶ past-future protected
 - ▶ pileup (up to 100 events)
 - ▶ within a bunch
 - ▶ within the drift time
- ▶ heavy ions
 - ▶ isolated events
 - ▶ multiplicity trigger

1 *pp* event3 *pp* events (pileup)1 *PbPb* event (θ -slice)

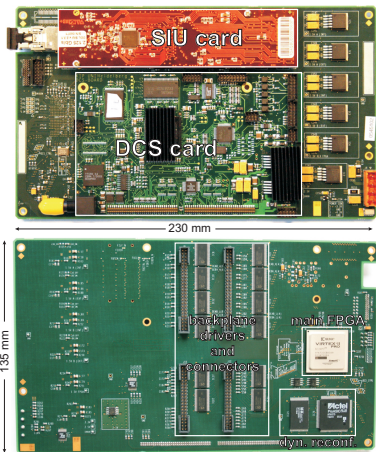
Foreseen operating scenarios – Simulations

- ▶ simulations done by merging $\sqrt{s} = 7$ TeV min. bias pp events
- ▶ proton-proton pileup
 - ▶ overlay of displaced events
 - ▶ equally spaced from $T - 100$ to $T + 100 \mu\text{s}$.
- ▶ heavy ions
 - ▶ overlay of events without displacement
 - ▶ 100 for min. bias $PbPb$, and
 - ▶ 300 for central collisions

1 pp event3 pp events (pileup)1 $PbPb$ event (θ -slice)

Read-out control unit (RCU)

- ▶ 216 RCUs, one per read-out partition
- ▶ 2 buses connect to half of the FECs each
- ▶ 2 daughter cards:
 - ▶ SIU card: optical link (DDL) interface to experiment-wide data acquisition
 - ▶ DCS card:
 - ▶ clock and trigger receiver
 - ▶ embedded Linux to monitor electronics
- ▶ 2 FPGAs:
 - ▶ Xilinx: communication to FECs and daughter cards
 - ▶ Actel: active partial reconfiguration to increase radiation tolerance



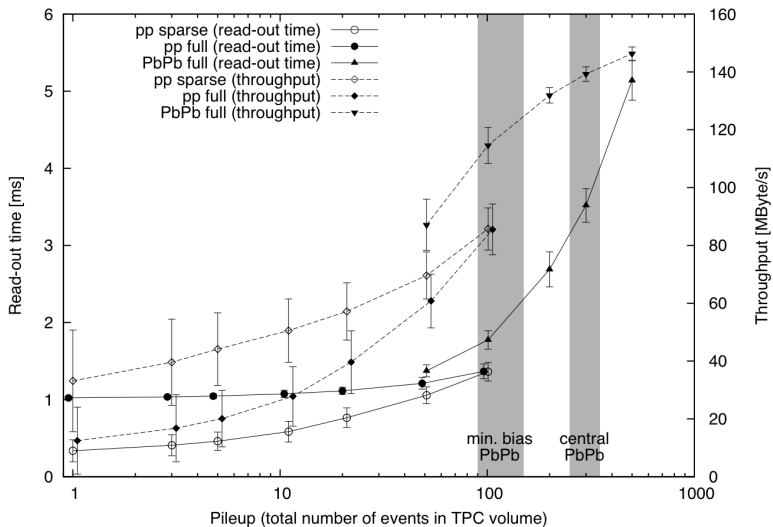
Read-out modes

- ▶ full read-out:
 - ▶ read out every channel ($T_{rdo,ch} \geq 450$ ns)
 - ▶ multiple event buffer usable
 - ▶ used for high occupancy events
- ▶ sparse read-out:
 - ▶ BCs compile lists of channels with data (parallel on all FECs) ($T_{sevl} = 90$ μ s)
 - ▶ BCs transfer list of active channels to RCU (total: $T_{revl} = 10$ μ s)
 - ▶ read-out of non-empty channels only
 - ▶ multiple event buffer not usable (FEC isolated during first point)
 - ▶ used for sparse events

Read-out times and throughput

- ▶ front-end electronics designed for *PbPb* events and rates of 100 – 300 Hz.
- ▶ read-out times measured by overlaying different numbers of events events in
 - ▶ in *pp* pileup topology (sparse and full read-out)
 - ▶ in *PbPb* topology (only full read-out)
- ▶ read-out time: maximum read-out time of all 216 links: $\max\{T_{rdo}\}$
- ▶ throughput: maximum link-size divided by maximum read-out time of all 216 links each: $\max\{S_{DDL}\}/\max\{T_{rdo}\}$

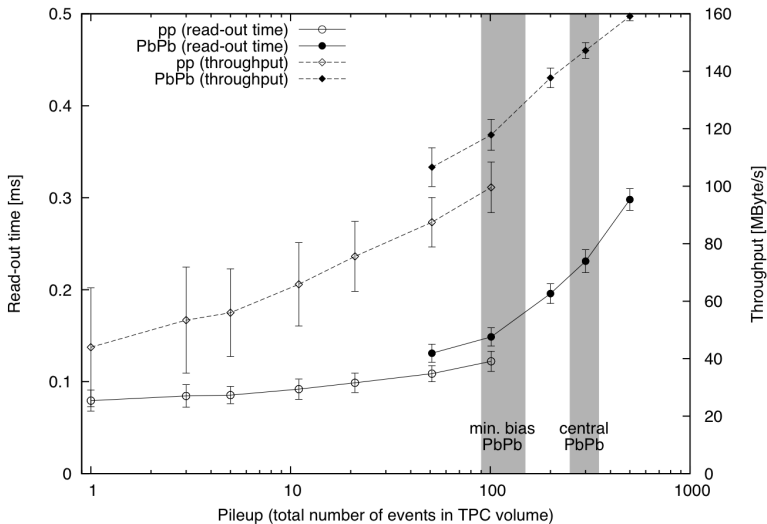
Read-out times and throughput – measurements



Motivations to upgrade

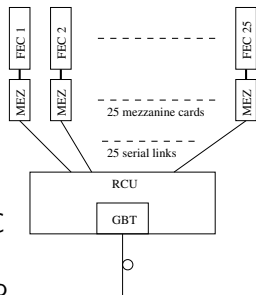
- ▶ physics:
 - ▶ lower expectation for $dN/d\eta$ for central $PbPb$ collisions: 2,500 instead of 8,000 (TDR)
 - ▶ stable operation of other similar devices observed at high rates
 - ▶ event selection by HLT
- ▶ electronics:
 - ▶ reduce impact of ALTRO protocol overhead
 - ▶ make better use of available (future) bandwidth
 - ▶ resolve full VS. sparse read-out issue
 - ▶ increase fault tolerance

Motivations to upgrade II: FEC performance



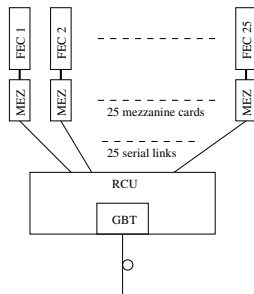
Proposed architecture

- ▶ restrictions:
 - ▶ keep FECs (worth 80% of whole TPC)
- ▶ topology:
 - ▶ replace bus by star
 - ▶ use serial links
- ▶ parts:
 - ▶ “FECint” (4,536): interface card to translate FEC bus to serial
 - ▶ “master RCU” (about 216): star-point and link to central services (Trigger, DAQ, DCS)



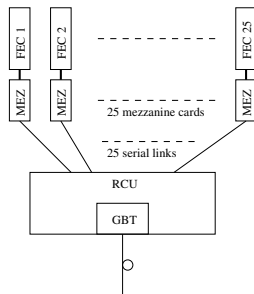
FECint

- ▶ translates parallel bus to serial bus
- ▶ adds memory to further derandomise events
- ▶ parallel interface to FEC:
 - ▶ clocks (sampling and read-out)
 - ▶ triggers
 - ▶ data
 - ▶ slow control
- ▶ serial link to master RCU:
 - ▶ 4 differential lines:
 - ▶ receive (2 GBit/s)
 - ▶ transmit (2 GBit/s)
 - ▶ *clock*
 - ▶ *trigger*
 - ▶ βC
- ▶ targets Xilinx Spartan-6 (cheap FPGA with high speed serial links)



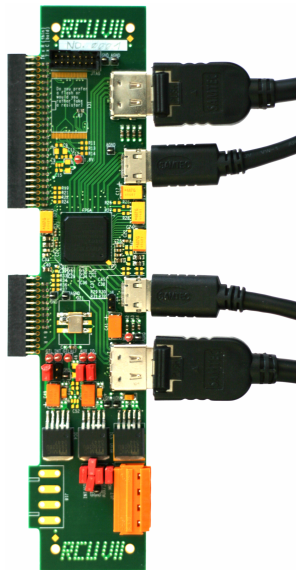
Master RCU

- ▶ star-point in data flow
- ▶ serial connection to about 20 FECs
- ▶ interface to central services, by (depending on DAQ upgrade) either:
 - ▶ integration of DDL and DCS, or
 - ▶ integration of new high level link
- ▶ integration into a single FPGA
- ▶ targets Xilinx Virtex-6



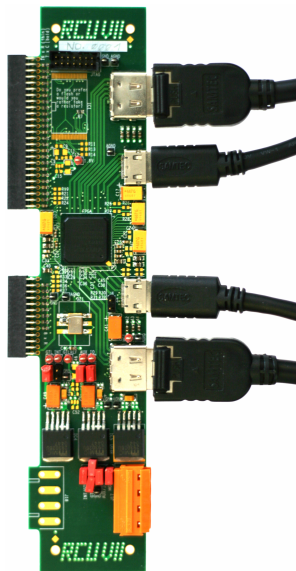
FECint prototype – design

- ▶ based on Virtex-II Pro (availability)
- ▶ aims:
 - ▶ mechanics:
 - ▶ minimum size
 - ▶ FEC connectors
 - ▶ choice of serial connectors
 - ▶ weight
 - ▶ electronics:
 - ▶ GTL-CMOS interfacing
 - ▶ signal integrity
 - ▶ price



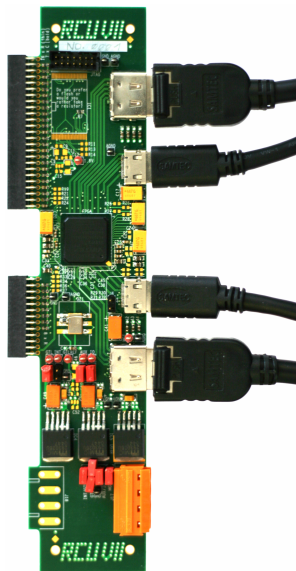
FECint prototype – hardware

- ▶ PCB:
 - ▶ dimensions: 18.4×4 cm
 - ▶ layers: 8 (to have enough power planes to assess decoupling)
- ▶ connectivity:
 - ▶ 4 serial ports:
 - ▶ 2 HDMI
 - ▶ 2 mHDMI
 - ▶ 2 rx-tx swapped
 - ▶ JTAG (programming and communication)
- ▶ testability features:
 - ▶ currents
 - ▶ voltages
 - ▶ FPGA temperature



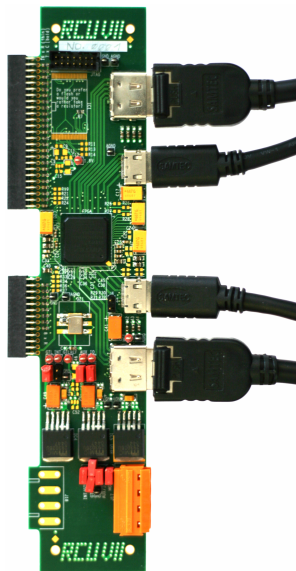
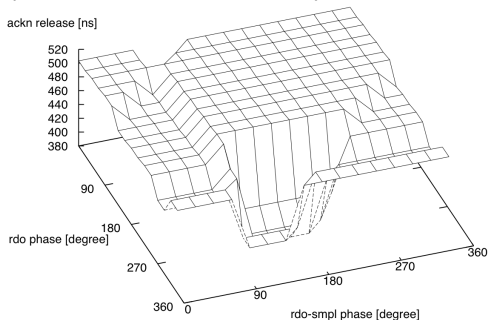
FECint prototype – firmware

- ▶ FEC link:
 - ▶ software controlled DCMs for phase shifts of read-out and sampling clocks
 - ▶ in system ALTRO bus state analyser
 - ▶ detailed phase scans and characterisation of transactions
- ▶ serial link:
 - ▶ simple data packet transmitter and receiver
 - ▶ power consumption and temperature monitoring



FECint prototype – results

- ▶ approach is feasible
- ▶ minor issues:
 - ▶ FEC-connectors: needs adjustment in height
 - ▶ PCB size need to be adjusted for cooling hoses
- ▶ improvement of ALTRO communication possible (due to direct connection):



Near future

- ▶ second iteration of the FECint:
 - ▶ Spartan-6
 - ▶ adjusted geometry (size and connectors)
 - ▶ cost-optimised routing
 - ▶ USB/SFP connectivity
- ▶ implementation of “master RCU”:
 - ▶ as counter part for the front-end link
 - ▶ including modules to interface Trigger and DAQ
- ▶ re-assessment with real PbPb data

Farer future

- ▶ 2012: qualification of components
- ▶ 2013: engineering of large scale prototype
- ▶ 2014–2015: production & testing
- ▶ 2016: installation (long LHC shutdown)